

<p>Marked-Up Copy</p> <p>Serial No: <u>09/539,864</u></p> <p>Amendment Filed on: <u>September 12, 2001</u></p>

IN THE SPECIFICATION

Page 5, please rewrite the paragraph at lines 16-23, as follows:

--Further, with the line width and the width between the lines being reduced, filler 4 having a still smaller particle diameter is demanded; however, the filler 4 can only be reduced in particle diameter to about 10 μm at the smallest, and if [a minute or five] one or five minutes of processing is performed in such a state, a problem also arises that the bonding strength between the insulating layer and the conductor layer is lowered.--

IN THE CLAIMS

Please cancel Claims 1-2.

Please add the following new claims:

--3. (New) to 22. (New) --